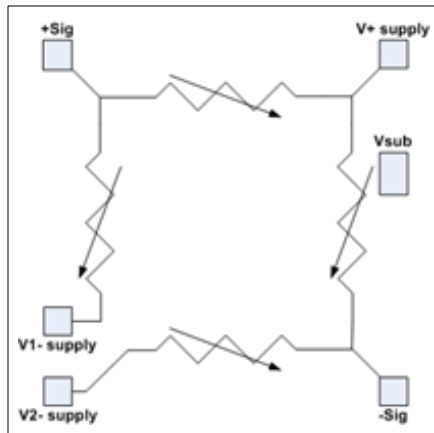
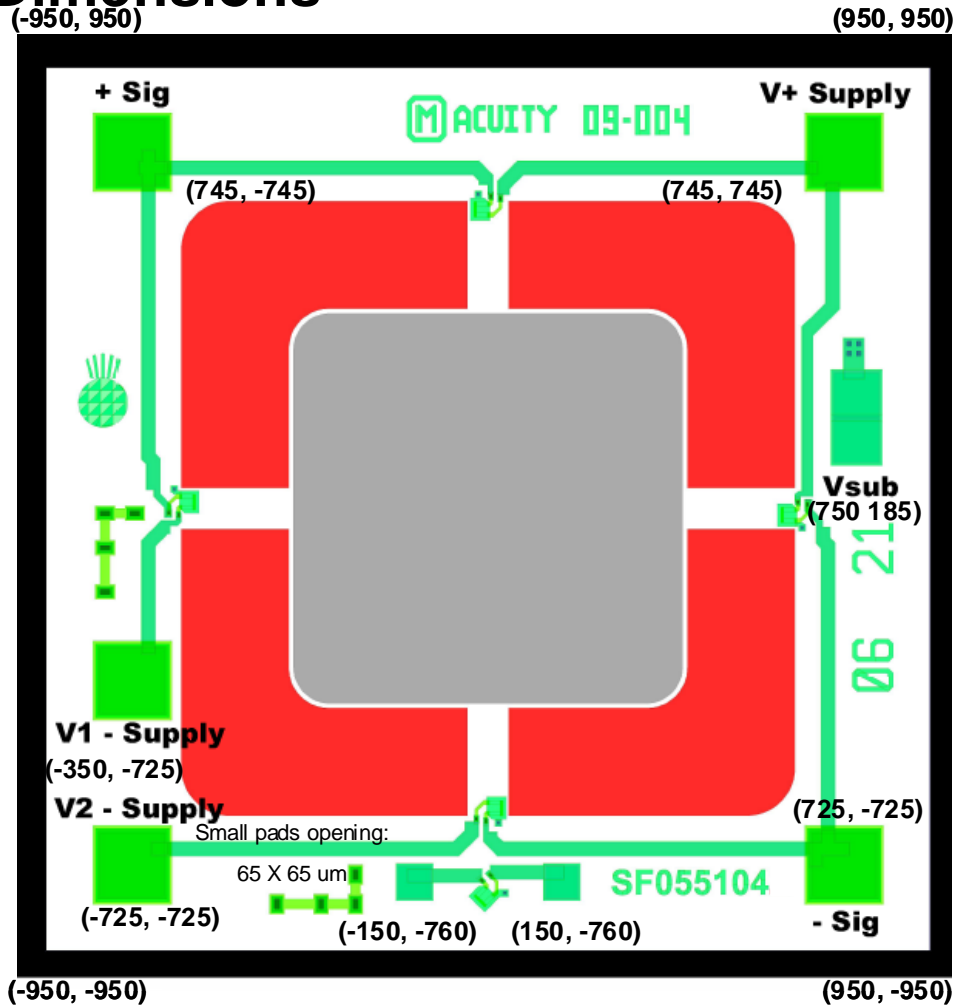
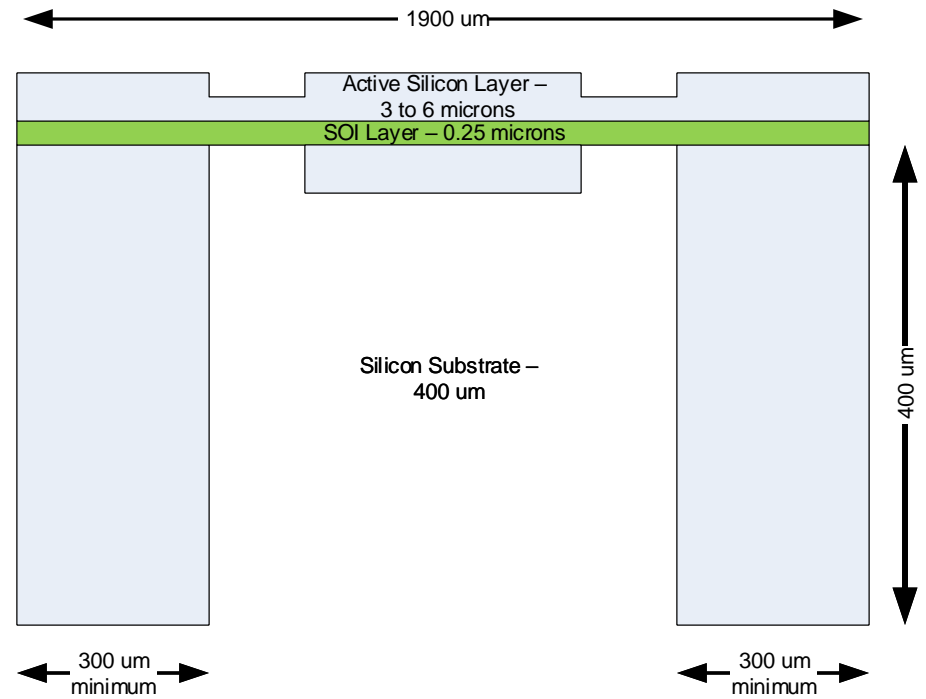


Dimensions



NOTE:

1. All dimensions are in μm .
2. The coordinates for the center of each pad, shown as (XXX,YYY), are with respect to the center of the die.
3. Pad size openings are $130 \times 130 \mu\text{m}$ except the substrate pad which is $90 \times 180 \mu\text{m}$.
3. + Signal increases and - Signal decreases when pressure is applied from the top of the die.
4. AC3050 and AC3055 have identical bond-pad locations.
5. For maximum performance, VSub should be tied to the highest voltage in the circuit..



Equivalent Circuit and Pad-outs



Acuity Incorporated
Fremont CA 94539 USA
www.acuitymicro.com

Acuity Incorporated

AC3050 Series
Dimensions and Pin-outs

Date: 21 Sept 17

By: HVAllen

Revision: B